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PMP8697_RevB BOM

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C1, C2, C8	3	10uF	CAP, CERM, 10uF, 25V, X7R	1210	Used in BOM report	Used in BOM report
C3, C9	2	DNP	CAP, [Technology], xxxF, xxV, +/-xx%, xxOhm ESR, [MountType]	Size Code C	Used in BOM report	Used in BOM report
C4	1	68uF	CAP, [Technology], xxxF, xxV, +/-xx%, xxOhm ESR, [MountType]	Used in PnP output	EKXG451ELL680MMN3S	Used in BOM report
C5, C6	2	0.15uF	CAP, Film, 0.15uF, 630V, +/-10%, TH	B32922_12mm	B32922C3154K	EPCOS Inc
C7	1	0.01uF	CAP, CERM, 0.01uF, 500V	1206	Used in BOM report	Used in BOM report
C10	1	560uF	CAP, [Technology], xxxF, xxV, +/-xx%, xxOhm ESR, [MountType]	Used in PnP output	25ZL660MX20	Used in BOM report
C11	1	22uF	CAP, CERM, 22uF, 16V, X7R	1210	Used in BOM report	Used in BOM report
C12	1	22uF	CAP, AL, 22uF, 25V, +/-20%, 1 ohm, SMD	SMT Radial D	EEE-FC1E220P	Panasonic
C13, C15	2	0.1uF	CAP, CERM, xxxF, 50V, X7R, xx%, [PackageReference]	0805	Used in BOM report	Used in BOM report
C14	1	DNP	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	0603	Used in BOM report	Used in BOM report
C16	1	0.01uF	CAP, CERM, xxxF, 50V, X7R, xx%, [PackageReference]	0805	Used in BOM report	Used in BOM report
C17	1	DNP	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	0805	Used in BOM report	Used in BOM report
D1, D4	2	STPS1150	Diode, Schottky, xxV, xxA, [PackageReference]	Used in PnP output	STPS1150A	Used in BOM report
D2, D5	2	20V	Diode, Zener, 18V, 225mW, SOT-23	SOT-23	BZX84C20LT1G	ON Semiconductor
D3	1	DF06S	Diode, Switching-Bridge, 600V, 1A, DF-S	DF-S	DF06S-E3	Vishay-Semiconductor
D6	1	US1J	Diode, Schottky, xxV, xxA, [PackageReference]	Used in PnP output	US1J	Used in BOM report
D7	1	MBRB8H100	Diode, Schottky, xxV, xxA, [PackageReference]	Used in PnP output	MBRB8H100	Used in BOM report
D8	1	MMSD914T1	Diode, Switching, 100-V, 200-mA, 225-mW,	SOD-123	MMSD914T1	On Semi
D9	1	MBR0520	Diode, Schottky, 20V, 0.5A, SOD-123	SOD-123	MBR0520LT1G	ON Semiconductor
D10	1	20V	Diode, Zener, 20V, 225mW, SOT-23	SOT-23	BZX84C20LT1G	ON Semiconductor
F1	1	1.25A	Fuse, Slow Blow,	0.335 inch	37211250001	Wickmann
L1	1	DNP	Coupled inductor, 600uH, 1A, 0.2 ohm, TH	Coupled inductor, 17.5x17x11mm	UU9.8V-601LF	GCI Technologies
L2	1	20 mH	Inductor, Common Mode Choke, 1.5 A, ±30%	13x23 mm	744823220	WE
Q1	1	SPD03N60C3	MOSFET, Nch, 650V, 3.2 mA, 1.4 Ohm	DPAK	SPD03N60C3	Infineon
Q2	1	MMBT3906	Transistor, PNP, 40V, 0.2A, SOT-23	SOT-23	MMBT3906	Fairchild Semiconductor
R1, R5	2	0	RES, xxx ohm, x%, xW, [PackageReference]	0805	Used in BOM report	Used in BOM report
R2	1	56	RES, xxx ohm, x%, xW, [PackageReference]	2512	Used in BOM report	Used in BOM report
R3	1	100k	RES, xxx ohm, x%, xW, [PackageReference]	2010	Used in BOM report	Used in BOM report
R4, R6, R7	3	1.5M	RES, xxx ohm, x%, xW, [PackageReference]	1206	Used in BOM report	Used in BOM report
R8	1	10	RES, xxx ohm, x%, xW, [PackageReference]	0805	Used in BOM report	Used in BOM report
R9	1	10	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R10	1	49.9	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R11	1	182k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R12	1	100k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R13	1	60.4k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R14	1	57.6k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R15	1	374k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R16, R17	2	20k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R18, R22	2	DNP	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R19, R20	2	0	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R21	1	11.5k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R101	1	2k	RES, xxx ohm, x%, xW, [PackageReference]	0805	Used in BOM report	Used in BOM report
RS	1	DNP	Thermistor,	0.590 x 0.276 inch	B57237xxxxxM000	Epcos
RV1	1	DNP	Varistor, Disk, 350V, 1W, TA @ 85C°	D Size	SIOV-S20K275	Epcos
T1	1	220 uH	Transformer, 220uH, TH	22.2X16X25 mm	750811932_00	Wurth Elektronik eiSos
TP1, TP4, TP9, TP10	4	Red	Test Point, TH, Miniature, Red	Keystone5000	5000	Keystone
TP2	1	Red	Test Point, TH, Multipurpose, Red	Keystone5010	5010	Keystone
TP3, TP6, TP11	3	Black	Test Point, Miniature, Black, TH	Black Miniature Testpoint	5001	Keystone
TP5	1	Black	Test Point, TH, Multipurpose, Black	Keystone5011	5011	Keystone
TP7, TP8	2	Double	Terminal, Turret, TH, Double	Keystone1503-2	1503-2	Keystone
U1	1	UCC28610D	IC, Quasi-Resonant Flyback Green-Mode Controller	SO8	UCC28610D	TI
U2	1	LMV431A	Low-Voltage (1.24V) Adjustable Precision Shunt Regulators, 3-pin SOT-23, Pb-Free	MF03A	LMV431AIMFX/NOPB	National Semiconductor

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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